

What Is Claimed Is:Sub
B1

1. An adhesive composition, comprising:
an insulating resin;
a photopolymerization initiator; and
an oxetan compound.

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2. The adhesive composition according to Claim 1,
comprising 5 to 50 wt% oxetan compound in 100 wt% adhesive
composition.

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3. The anisotropic conductive adhesive composition
according to ^{Claim 1}~~Claim 1 or Claim 2~~, further comprising
electrically conductive particles.

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4. A connected structure, wherein electrodes on a
plastic substrate and on a circuit board that are facing each
other are connected by the adhesive composition according to
^{Claim 1}~~any of Claims 1 to 3.~~

Add A1

Add B4

Add C2